

# Product / Process Change Notification



N° 2020-016-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## Capacity Extension for Dedicated OptiMOS™ Products in PG-TSDSON-8 Package at Tongfu Microelectronics Co. Ltd China

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **3<sup>rd</sup> November 2020**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:  
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG  
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Chairman of the Supervisory Board: Dr. Wolfgang Eder  
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider  
Registered Office: Neubiberg  
Commercial Register: München HRB 126492

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► **Products affected:**

Please refer to attached affected product list 1\_cip20016\_A



► **Detailed Change Information:**

**Subject:** Capacity Extension for Dedicated OptiMOS™ Products in PG-TSDSON-8 Package at Tongfu Microelectronics Co. Ltd China

**Reason:** Expansion of assembly and test production to cover increasing customer demand, and enable flexible manufacturing

**Description:**

Old

New

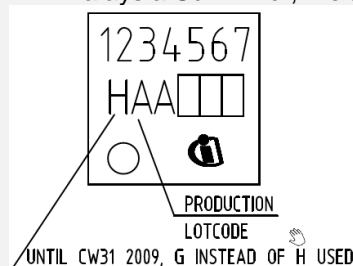
**Assembly and Final Test location**

- Infineon Technologies Malaysia Sdn. Bhd., Melaka

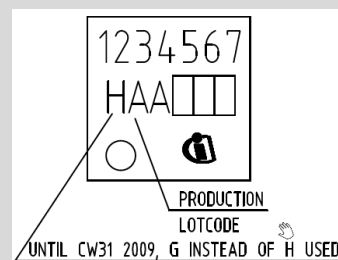
- Infineon Technologies Malaysia Sdn. Bhd., Melaka
- Subcontractor Tongfu Microelectronics Co. Ltd.,China

**Marking on device**

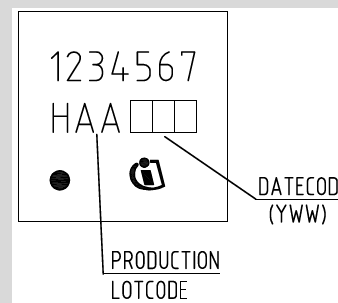
- Infineon Technologies Malaysia Sdn. Bhd., Melaka



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## Package Outline Drawing

Please refer to 3\_cip20016\_a on minor update of the datasheet package drawing.

## ▶ Product Identification:

Internal traceability via Baunumber, Lotnumber, date code and marking on device

External traceability via the marking on device

## ▶ Impact of Change:

**NO** change on electrical, thermal parameters and reliability as proven via product qualification and characterization.

**NO** change of electrical parameters in the datasheet.

**NO** change in quality and device processability at customer end.

Assembly processes are optimized to meet product performance according to already applied Infineon specification.

**Update** of package outline drawing in the datasheet.

## ▶ Attachments:

1\_cip20016\_a Affected product list

2\_cip20016\_a Qualification Report

3\_cip20016\_a Customer Information Package

(detailed change description of product identification and package outline drawing comparison)

## ▶ Time Schedule:

■ Final qualification report:

Available

■ First samples available:

On request

■ Intended start of delivery:

31-October-2020 or earlier based on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.